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Dual Operational Amplifier, 7 MHz Bandwidth with Shutdown

NCS20282

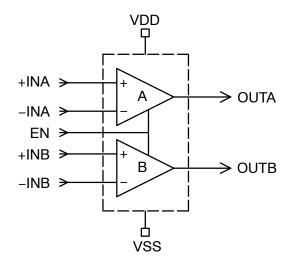
The NCS20282 high precision op amp features a wide bandwidth along with shutdown. These amplifiers provide low bias current useful for transimpedance applications. The wide bandwidth eases the design of active filters. The NCS20282 is specified for operation from -40°C to +125°C.

Features

- High Bandwidth: 7 MHz typical
- Low Bias Current: 50 pA typical
- Rail-to-Rail Input/Output
- Shutdown Current: 1 µA max
- Offset Voltage: 1.5 mV max
- Offset Drift: 10 µV/°C max
- Supply Voltage: 2.5 V to 5.5 V
- These Devices are Pb-free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Transducer Applications
- Sensor Conditioning
- Medical Instrumentation
- Impedance Sensing





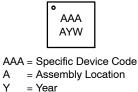
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WLCSP9 CASE 567YD

MARKING DIAGRAM

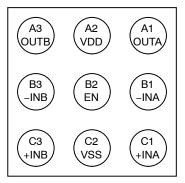




Α

(Note: Microdot may be in either location)

PIN CONNECTIONS



Package Bottom View (Bump Up)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 9 of this data sheet.

This document contains information on some products that are still under development. ON Semiconductor reserves the right to change or discontinue these products without notice.

Table 1. ABSOLUTE MAXIMUM RATINGS Over operating free-air temperature, unless otherwise stated.

Parameter	Rating	Unit V	
Supply Voltage (VDD- VSS)	7		
INPUT AND OUTPUT PINS			
Input Voltage (Note 1)	$(V_{SS}-0.5)$ to 7	V	
Input Current (Note 1)	±5	mA	
Output Pin Voltage, Disabled	7	V	
Output Short Circuit Current (Note 2)	Continuous		
TEMPERATURE			
Operating Temperature	-40 to +125	°C	
Storage Temperature	-65 to +150	°C	
Junction Temperature	+150	°C	
ESD RATINGS (Note 3)			
Human Body Model (HBM)	2000	V	
Charged Device Model (CDM)	1000	V	
OTHER RATINGS			
Latch-up Current (Note 4)	100		
MSL	Level 1		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The input voltage at any pin may exceed the voltage shown if the current at that pin is limited to 5 mA.

2. Short-circuit to ground.

3. This device series incorporates ESD protection and is tested by the following methods:

ESD Human Body Model tested per JEDEC standard JS-001-2017

ESD Charged Device Model tested per JEDEC standard JS-002-2014

4. Latch-up Current tested per JEDEC standard: JESD78

Table 2. THERMAL INFORMATION

Parameter	Symbol	Cu Area mm ²	1.0 oz	2.0 oz	Unit
Thermal Resistance	Θ_{JA}	10	301	263	°C/W
Junction to Ambient		25	263	230	
		40	246	215	
		80	229	204	
		140	220	196	
		250	211	188	
		350	206	183	
		500	200	179	
		650	197	175	1
		800	194	173	

NOTE: Four layer JSEC JESD51-7

Table 3. OPERATING CONDITIONS

Parameter	Symbol	Range	Units
Supply Voltage (V _{DD} – V _{SS})	V _S	2.5 to 5.5	V
Specified Operating Temperature Range	T _A	-40 to +125	°C
Input Common Mode Voltage Range	V _{CM}	V_{SS} to V_{DD}	V

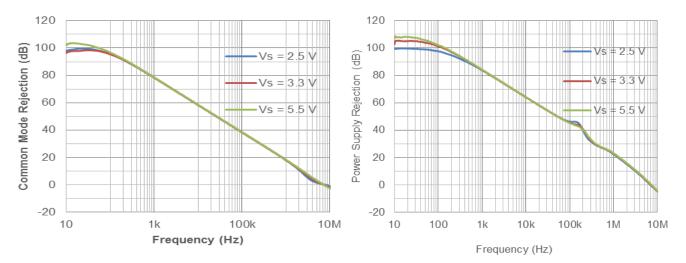
Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 4. ELECTRICAL CHARACTERISTICS: $V_S = 2.5 V$ to 5.5 VAt $T_A = +25^{\circ}C$, $R_L = 10 k\Omega$, $V_{CM} = V_{OUT}$ = midsupply, Enable input connected to V_{DD} , unless otherwise noted. **Boldface** limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+125^{\circ}C$, guaranteed by characterization and/or design

Parameter		Symbol	Condit	tions	Min	Тур	Max	Units	
INPUT CHARACTERISTIC	S		-			-			
Offset Voltage		V _{OS}				300	1500	μV	
Offset Voltage Drift vs Temp		$\Delta V_{OS} / \Delta T$				2	10	μV/°C	
Input Bias Current (Note 5)		I _{IB}				50	800	pА	
Input Offset Current		I _{OS}				10		pА	
Input Common-Mode Volta	ge Range	V _{CM}				V_{SS} to V_{DD}		V	
Common Mode Rejection F	latio	CMRR	$V_{CM} = -0.1 V to$	o (V _{DD} +0.1V)	66	86		dB	
Input Resistance		R _{IN}	Differe	ential		10		GΩ	
			Commor	n Mode		10			
Input Capacitance		C _{IN}	Differe	ential		2		pF	
			Commor	n Mode		5			
OUTPUT CHARACTERIST	ICS								
Open Loop Voltage Gain		A _{VOL}	$0.4 V \le V_{OUT} \le$	$V_{DD} - 0.4 V$	96	116		dB	
Closed Loop Output Imped	ance	Z _{OUT_CL}	See Fig	ure 23		See Figure 23		Ω	
Output Voltage High, Refer	enced to V _{DD}	V _{OH}				V _{DD} -3	V _{DD} -10	mV	
Output Voltage Low, Refere	enced to V _{SS}	V _{OL}				V _{SS} +6	V _{SS} +10	mV	
Short Circuit Current (Note	5)	I _{SC}	Sinking C	Current		10	15	mA	
			Sourcing	Current		10	15		
Capacitive Load Drive (Not	e 5)	CL				100	300	pF	
DYNAMIC PERFORMANC	E								
Gain Bandwidth Product (N	ote 5)	GBW	$\label{eq:VS} \begin{array}{l} V_S = 3 \ V; \\ R_L = 10 \ k\Omega, \ C_L = 100 \ pF \end{array}$		5.4	7		MHz	
Gain Margin		A _M	C _L = 10	00 pF		50		dB	
Phase Margin		Ψ_{M}	C _L = 10	00 pF		55		0	
Slew Rate		SR	A _V = +1			5		V/μs	
Overload Recovery Time		t _{OR}	$V_{IN} X A_V > V_S$			1		μs	
NOISE PERFORMANCE									
Voltage Noise Density		e _N	f _{IN} = 10 kHz			20		nV/√H:	
Current Noise Density		i _N	f _{IN} = 1			300		fA/√Hz	
POWER SUPPLY			-						
Power Supply Rejection Ratio		PSRR			90	120		dB	
Shutdown Enable Time (Notes 5, 6)		t _{ON}				30	50	μs	
Shutdown Disable Time (Note 6)		t _{OFF}				30		μs	
Shutdown LeakageInput $V_{IN} = V_S + 400 \text{ mV}$ Output $V_{OUT} = V_S + 1 \text{ V}$			V _{IN} = V _S +	400 mV			500	nA	
				500					
Enable Input Threshold Voltage		V _{th(EN)}	Operating		1.3			V	
			Disabled				0.5		
Enable Input Leakage Current		I _{Enable}	Enable = + 5.0 V			1.1		μA	
			Enable	= V _{SS}		1.1			
Quiescent Current		Ι _Q	Per Channel	Quiescent		850	1300	μA	
			No load	Shutdown		0.3	1		

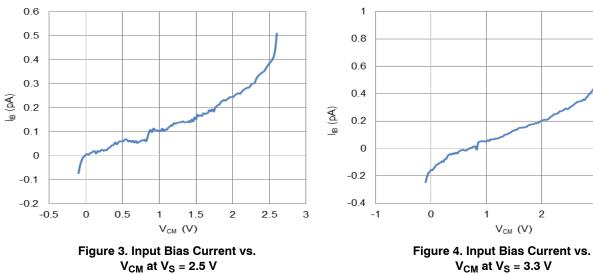
Guaranteed by design and/or characterization
Shutdown Disable Time (t_{OFF}) and Enable Time (t_{ON}) are defined as the time between the 50% point of the signal applied to the EN pin and the point at which the output voltage reaches the 10% (disable) or 90% (enable) level.
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

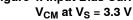
TYPICAL CHARACTERISTICS











1

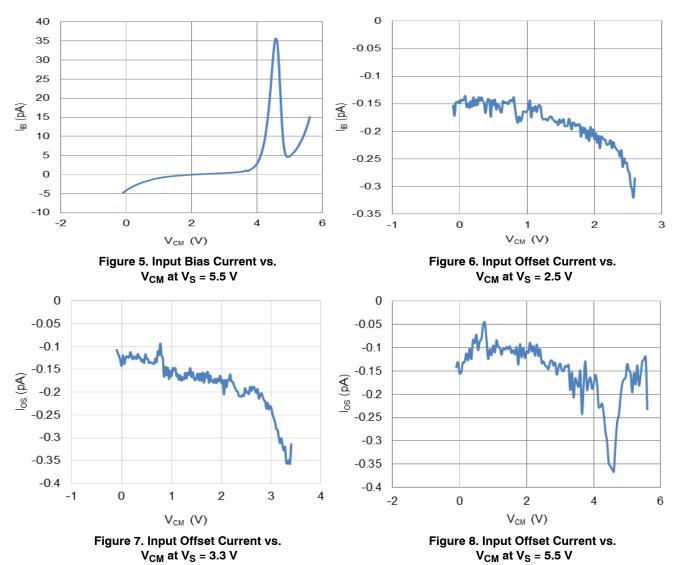
 V_{CM} (V)

2

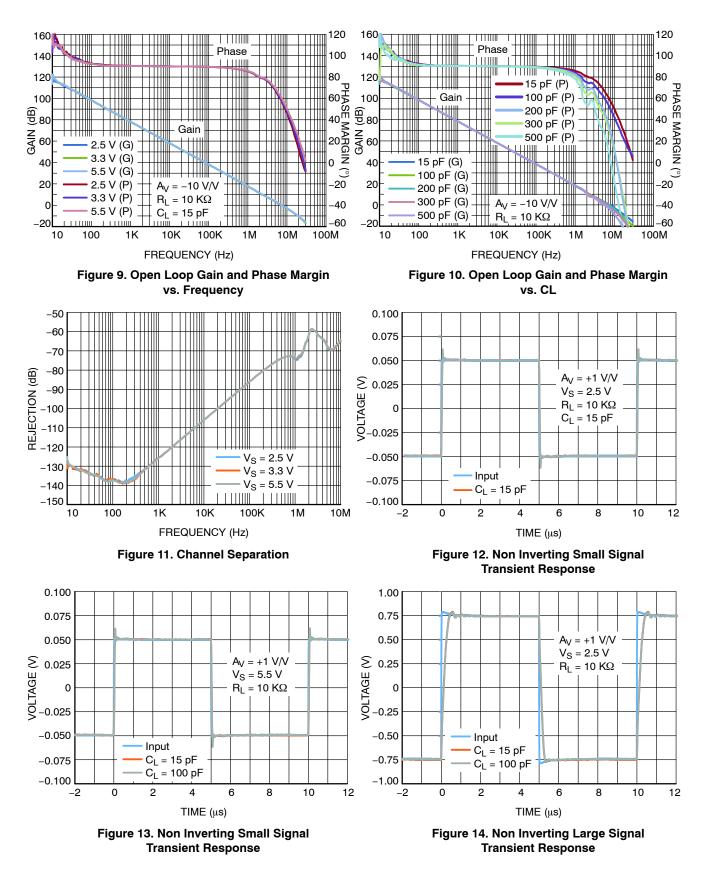
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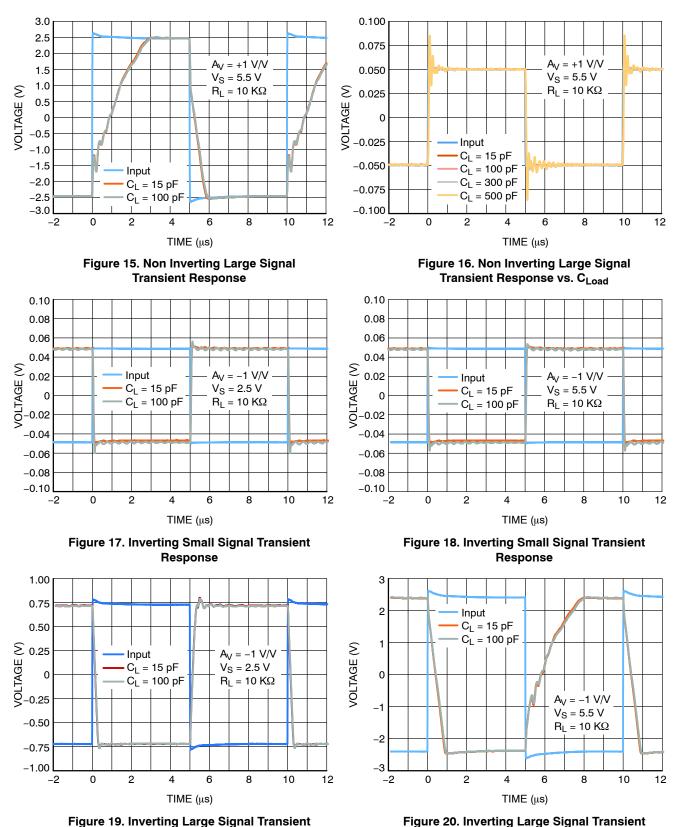
4





TYPICAL CHARACTERISTICS

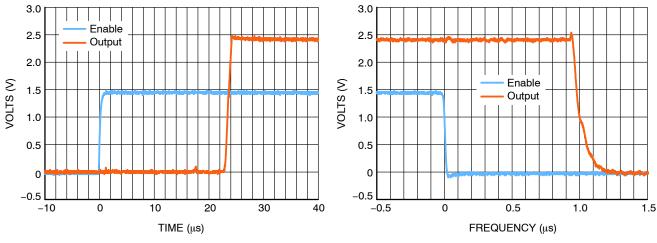




TYPICAL CHARACTERISTICS

Response

Response



TYPICAL CHARACTERISTICS





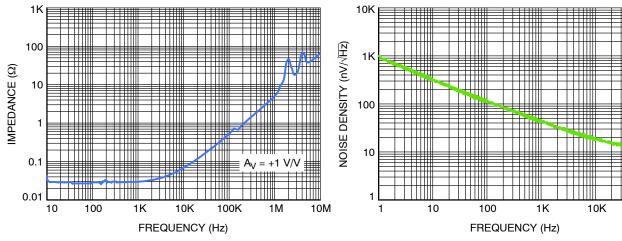


Figure 23. Closed Loop Output Impedance

Figure 24. Voltage Noise Density vs. Frequency

100K

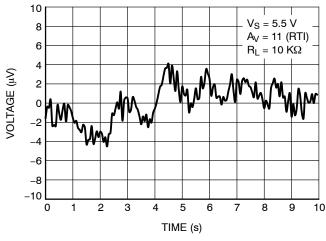


Figure 25. 0.1 Hz to 10 Hz Noise

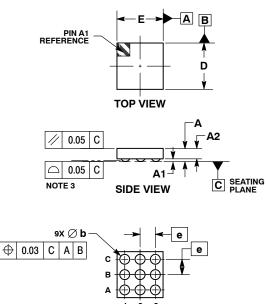
DEVICE ORDERING INFORMATION

Device	Marking	Bump Type	Case Outline	Package	Shipping [†]
NCS20282FCTTAG	AAA	Sn Plate	567UW	WLCSP-9 (Pb-Free)	5000 / Tape & Reel
NCS20282FCSTAG* (In Development)	AAA	SAC 405	567YD	WLCSP-9 (Pb-Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

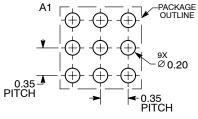
WLCSP9, 1.02x1.02x0.33 CASE 567UW **ISSUE A**



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

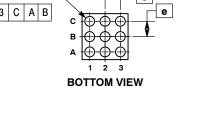
	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α			0.33	
A1	0.04	0.06	0.08	
A2	0.23 REF			
b	0.180	0.200	0.220	
D	0.99	1.02	1.05	
Е	0.99	1.02	1.05	
e	0.35 BSC			

RECOMMENDED SOLDERING FOOTPRINT*



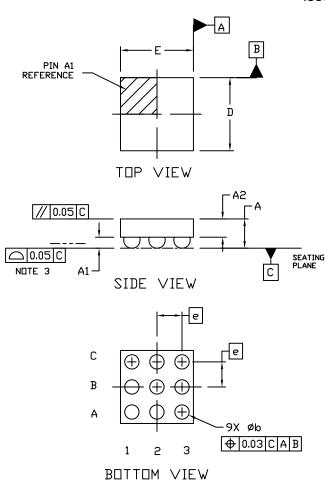
DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



PACKAGE DIMENSIONS

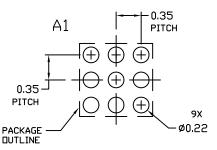
WLCSP9, 1.02x1.02x0.441 CASE 567YD ISSUE O



NDTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

	MILLIMETERS			
DIM	MIN.	NDM.	MAX.	
Α			0.441	
A1	0.133	0.153	0.173	
A2	0.255 REF			
b	0.183	0.203	0.223	
D	0.99	1.02	1.05	
E	0.99	1.02	1.05	
e	0.35 BSC			



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the UN Semiconductor Soldering and Mounting Techniques Reference Manual, SULDERRM/D.

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